



Press Release

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Live demonstrations of encapsulating, heat dissipating hot melt material

Henkel Thermal Management, Interconnect and Protection Materials on Show at SMT Hybrid Packaging 2018

Düsseldorf, Germany – Exhibiting in Hall 4, Booth 4-241 with distributor partner AAT Aston, Henkel Adhesive Electronics brings a wide range of enabling electronics assembly materials to the [SMT Hybrid Packaging](#) show, taking place June 5 – 7, 2018. The company will highlight its latest dual-function [TECHNOMELT®](#) product, [thermal interface material](#) (TIM) innovations and award-winning solder formulations, as well as take part in two panel discussions that focus on the importance of solder capability for void and defect reduction.

Substrate Protection and Thermal Management

Show delegates interested in learning more about the simplicity and effectiveness of Henkel's TECHNOMELT low pressure molding materials should plan to see live demonstrations of the thermally-conductive TECHNOMELT TC 50 at the AAT Aston stand. Utilizing an LPMS low pressure molding system, Henkel technical experts will illustrate the ease of the three-step overmolding process, which encapsulates substrates and circuitry to offer robust protection from various environmental factors. In addition to critical electronic safeguarding, TECHNOMELT TC 50 also conducts heat. A streamlined replacement for conventional potting materials, TECHNOMELT TC 50 provides >0.5 W/m-K thermal conductivity to dissipate heat through the encapsulating material.

Capable thermal management is critical for the performance and reliability of modern electronic devices in multiple sectors such as lighting, automotive, consumer and industrial, among others. In addition to TECHNOMELT TC 50, Henkel's line of BERGQUIST thermal interface materials including award-winning GAP PAD products and liquid gap fillers, as well as thermal films and adhesives, will be on display at the SMT show in Nuremberg. The portfolio is extremely broad, with numerous material mediums and thermal conductivity levels to address a variety of applications, device architectures and production preferences.

Interconnect Advances and Expertise

As the market-leading developer of game-changing solder technologies, Henkel is looking forward to showcasing its portfolio of [LOCTITE® GC](#) temperature stable solder paste formulations with booth visitors. Since their introduction, multi-award-winning LOCTITE GC 10 and water-washable LOCTITE GC 3W have made thousands of assembly processes more cost-effective, reliable and stable by delivering high-performance and temperature stability throughout the entire logistics and production value chain.

The company's solder know-how will also be featured during live show-floor Q&A sessions, as Henkel Global Technical Champion, Richard Boyle, is set to take part in two solder-related discussion panels. The below expert roundtables are free to attend and hosted by Global SMT and Packaging magazine in Hall 4, Booth 4-520:

- **Wednesday, June 6th, 10:00 a.m. – A Multi-disciplinary Approach to Void Reduction**
It is widely accepted that void reduction is best achieved through a combination of flux, alloy and soldering methodologies. The panel will discuss the merits of each and various techniques used to limit the formation of voids.
- **Thursday, June 7th, 10:30 a.m. – Stencils and Avoiding Printing Defects**
Recognizing the impact that the printing process has on defect rates, the panel will discuss best practices used to minimize defects and errors. Insufficient paste, beading, paste types and storage, cleaning cycles and methodologies, step stencil production and more will be addressed.

To learn more about Henkel's complete portfolio of electronics assembly and semiconductor solutions, visit www.henkel-adhesives.com/electronics. Schedule an appointment with the Henkel team at SMT Hybrid Packaging by sending an e-mail to berit.hoffman@henkel.com or calling +49 (4101) 803-285.

About Henkel

Henkel operates globally with a well-balanced and diversified portfolio. The company holds leading positions with its three business units in both industrial and consumer businesses thanks to strong brands, innovations and technologies. Henkel Adhesive Technologies is the global leader in the adhesives market – across all industry segments worldwide. In its Laundry & Home Care and Beauty Care businesses, Henkel holds leading positions in many markets and categories around the world. Founded in 1876, Henkel looks back on more than 140 years of success. In 2017, Henkel reported sales of 22.6 billion US dollars (20 billion euros) and adjusted operating profit of around 3.9 billion US dollars (3.5 billion euros). Combined sales of the respective top brands of the three business units – Loctite®, Schwarzkopf® and Persil® – amounted to 7.2 billion US dollars (6.4 billion euros). Henkel employs more than 53,000 people globally – a passionate and highly diverse team, united by a strong

company culture, a common purpose to create sustainable value, and shared values. As a recognized leader in sustainability, Henkel holds top positions in many international indices and rankings. Henkel's preferred shares are listed in the German stock index DAX. For more information, please visit www.henkel.com.

Photo material is available at <http://www.henkel.com/press>.

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